



# Design and Production of Pixel Strips for the P2 Tracking Detector Modules



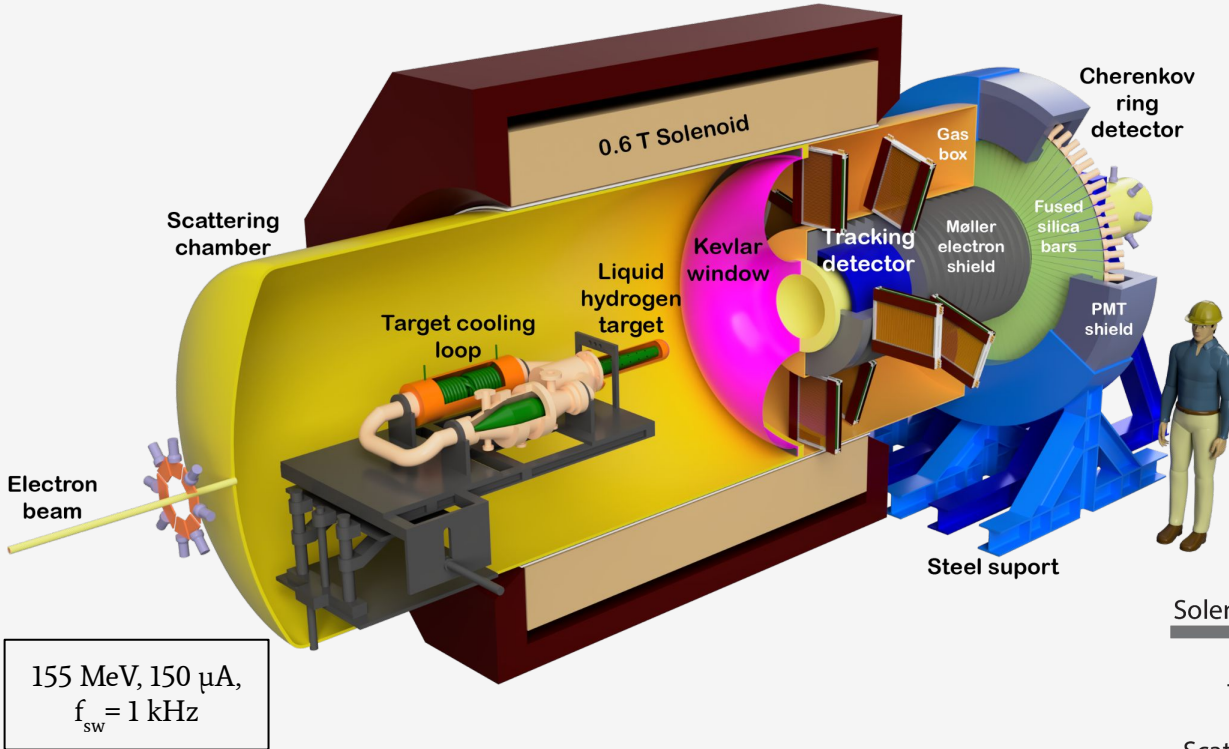
DPG Spring Meeting 2023

Lucas Sebastian Binn

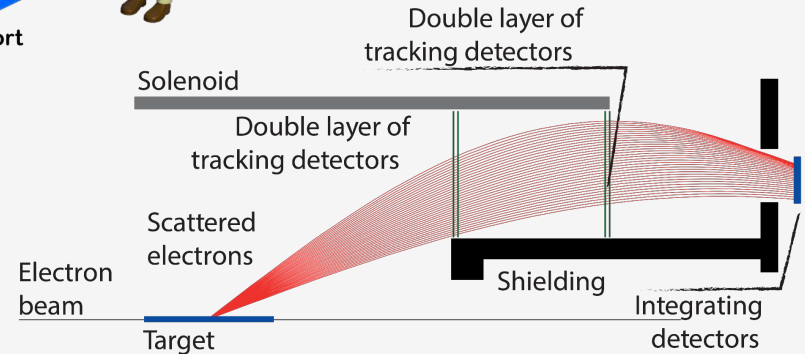
Johannes Gutenberg University Mainz



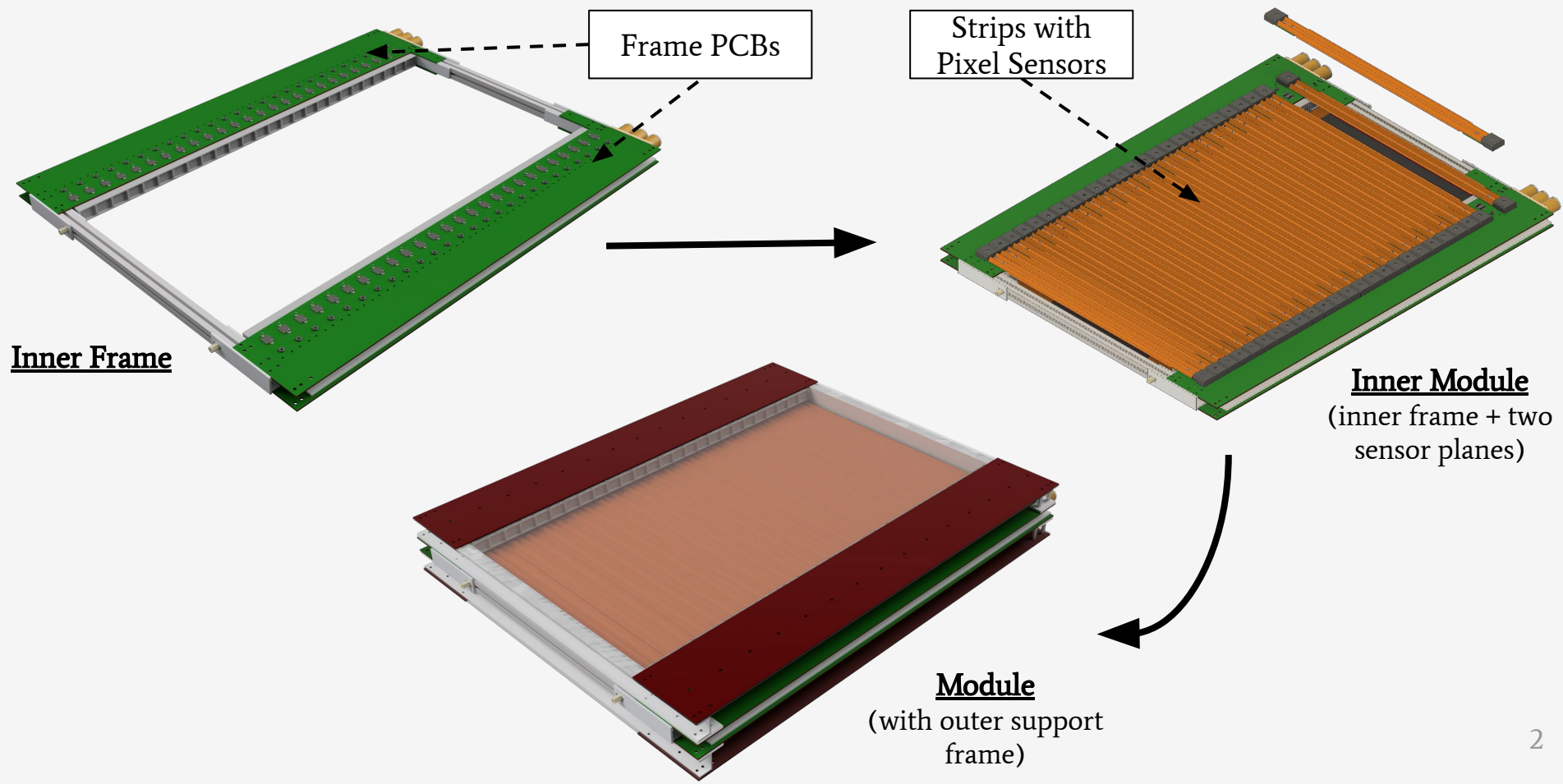
# P2 Experiment



- Located @ MESA in Mainz
- Determination of weak mixing angle at low momentum transfer
- Measure parity violating asymmetry in elastic electron-proton scattering
- Tracking Detector
  - Determination of average momentum transfer  $Q^2$
  - Study of systematic effects

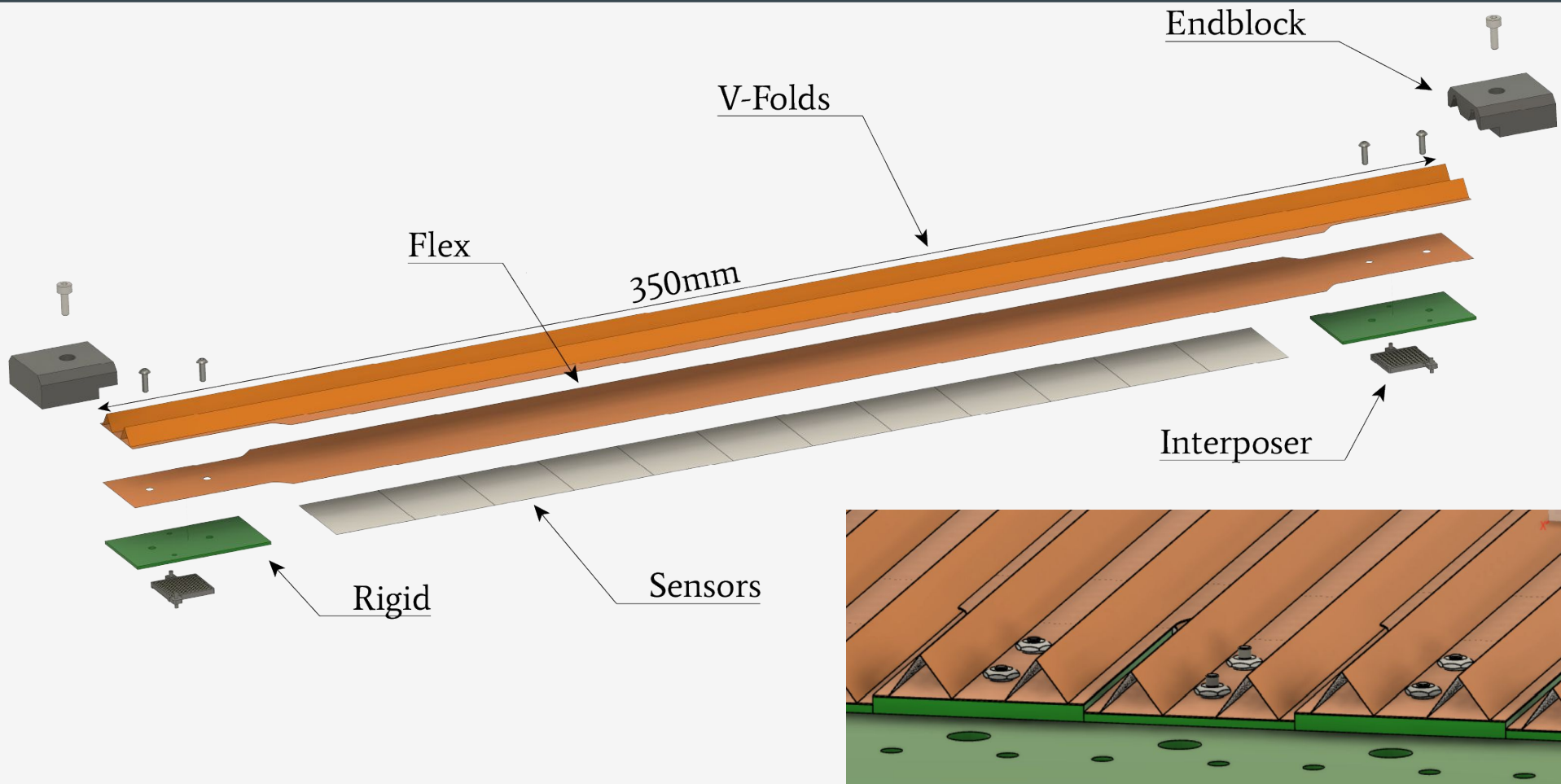


# Tracking Detector Module

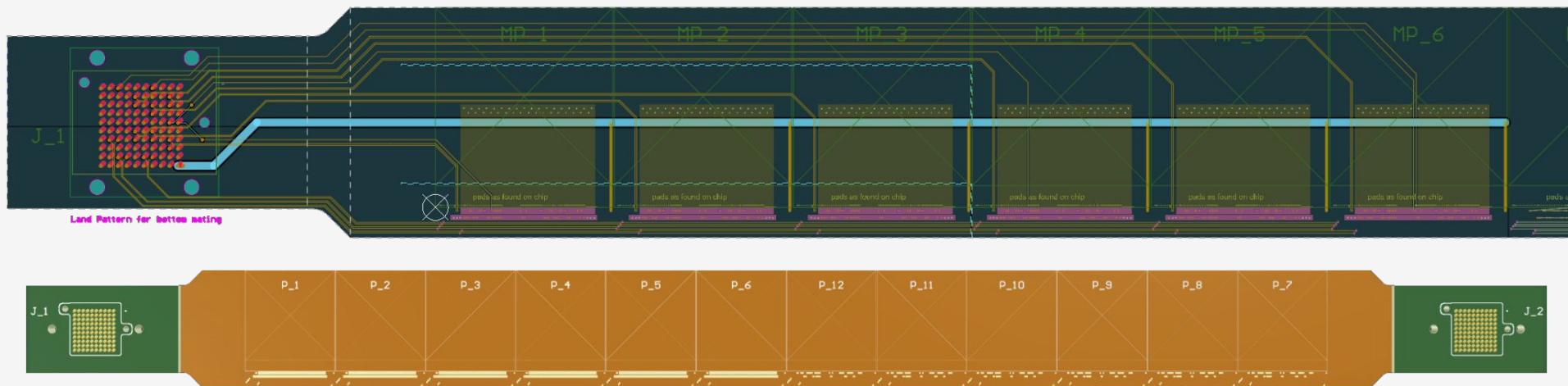




# Structure of the Strips



# Specifications

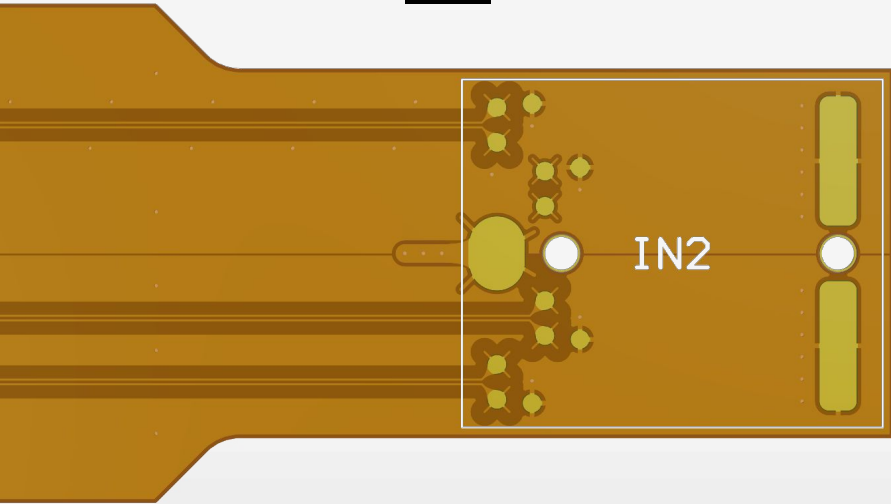


- Two layer flex (with rigid parts at the ends)
- 9  $\mu\text{m}$  copper thickness, 25  $\mu\text{m}$  dielectric  $\rightarrow X_0 = 1.45\%$
- Commercially available production of rigid-flex comes with compromises

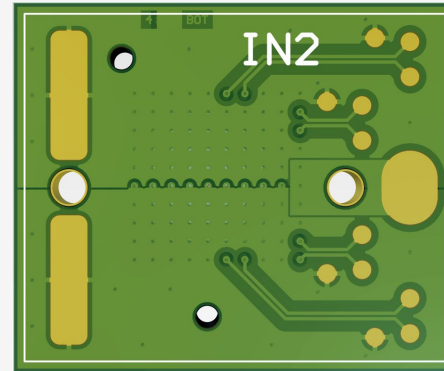
$\rightarrow$  idea to solder rigid-flex ourselves

# Soldered Rigid-Flex

Flex

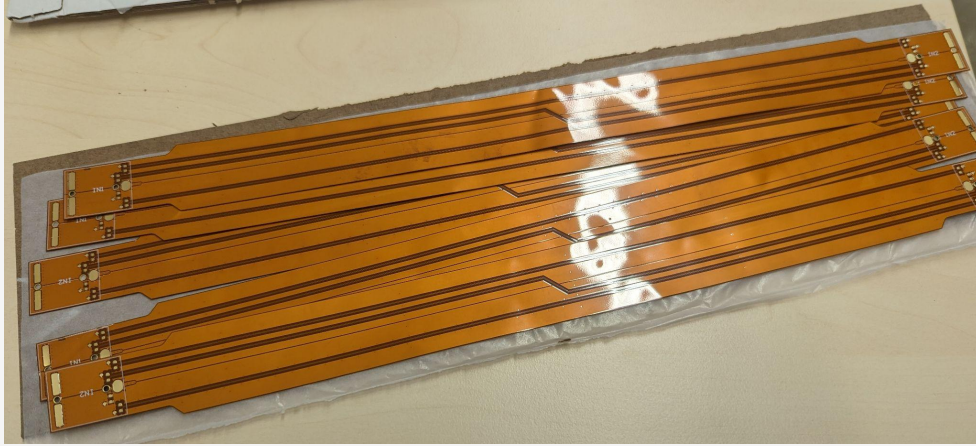


Rigid

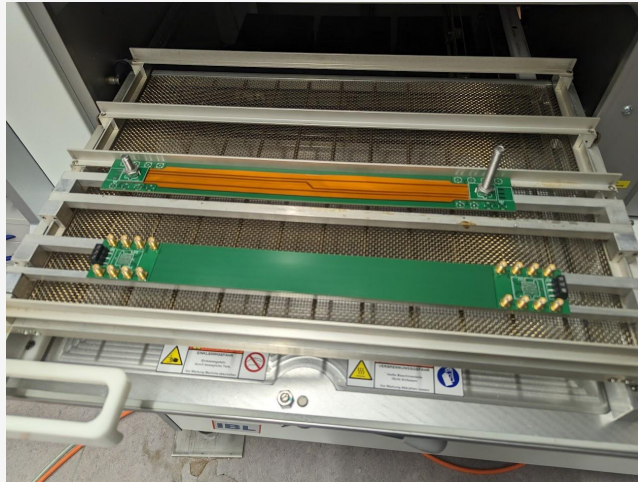
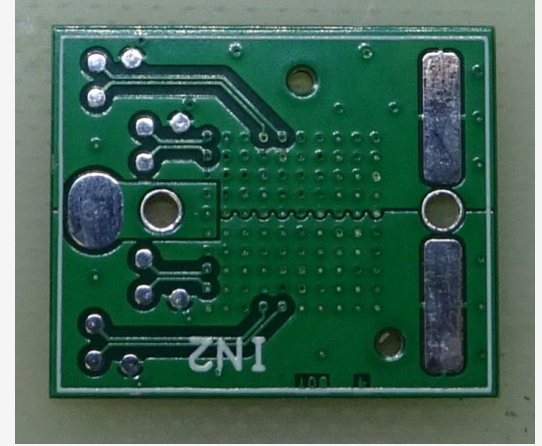


Solder matching patterns using  
reflow oven.

# Soldered Rigid-Flex



+



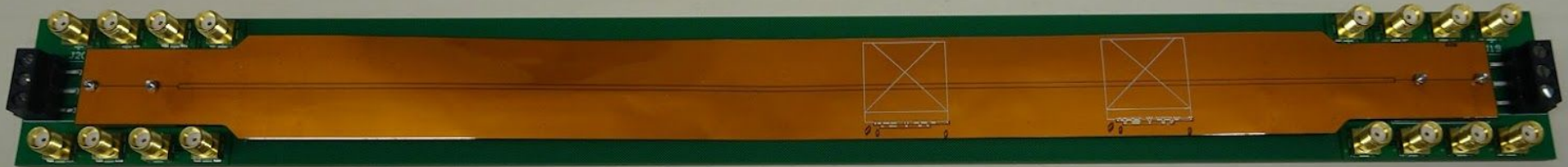


# Soldered Rigid-Flex

## Rigid-Flex

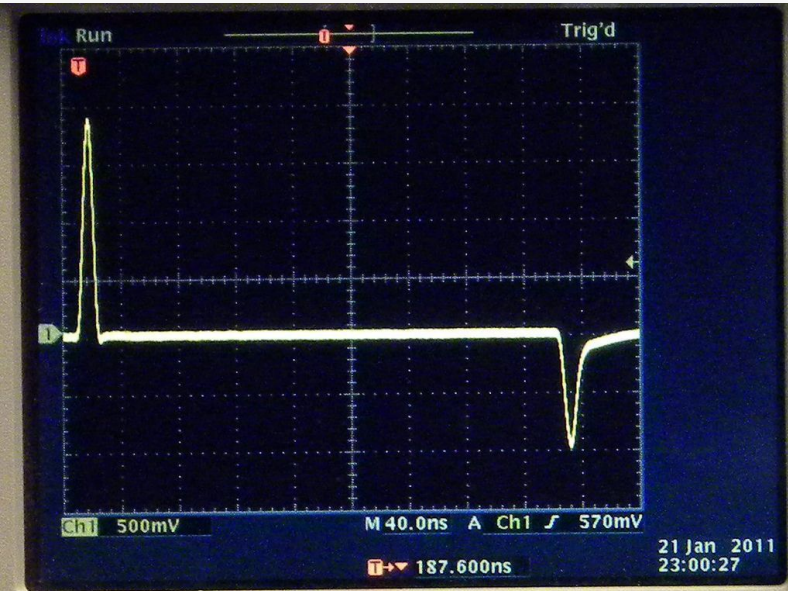


## Test Jig (with mounted rigid-flex)



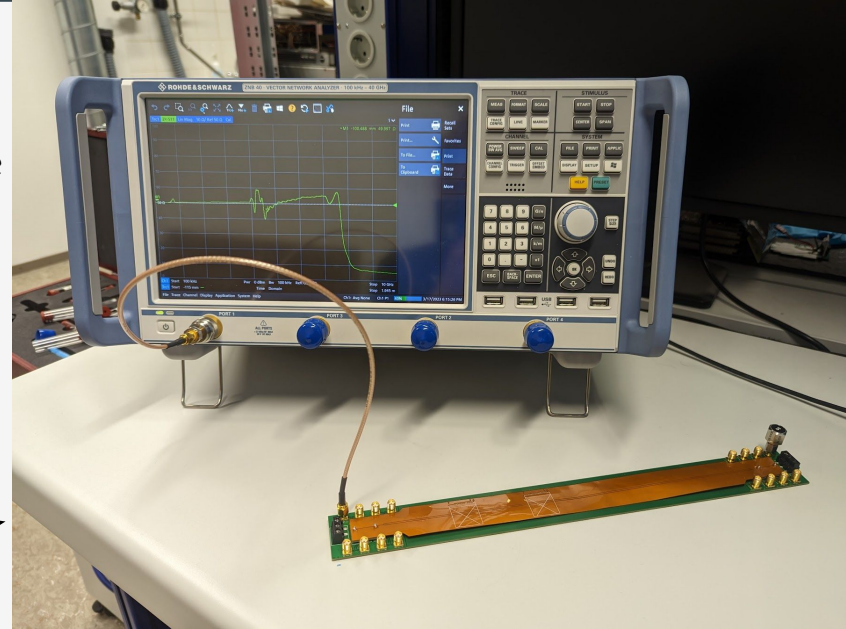
# Time Domain Reflectometry

- Non-invasive characteristic impedance measurement along conductor
- Reflection of signal at change of characteristic impedance
- Verify differential line impedance (constant) (signal integrity @ 1.25 Gbit/s)



[Oscilloscope]

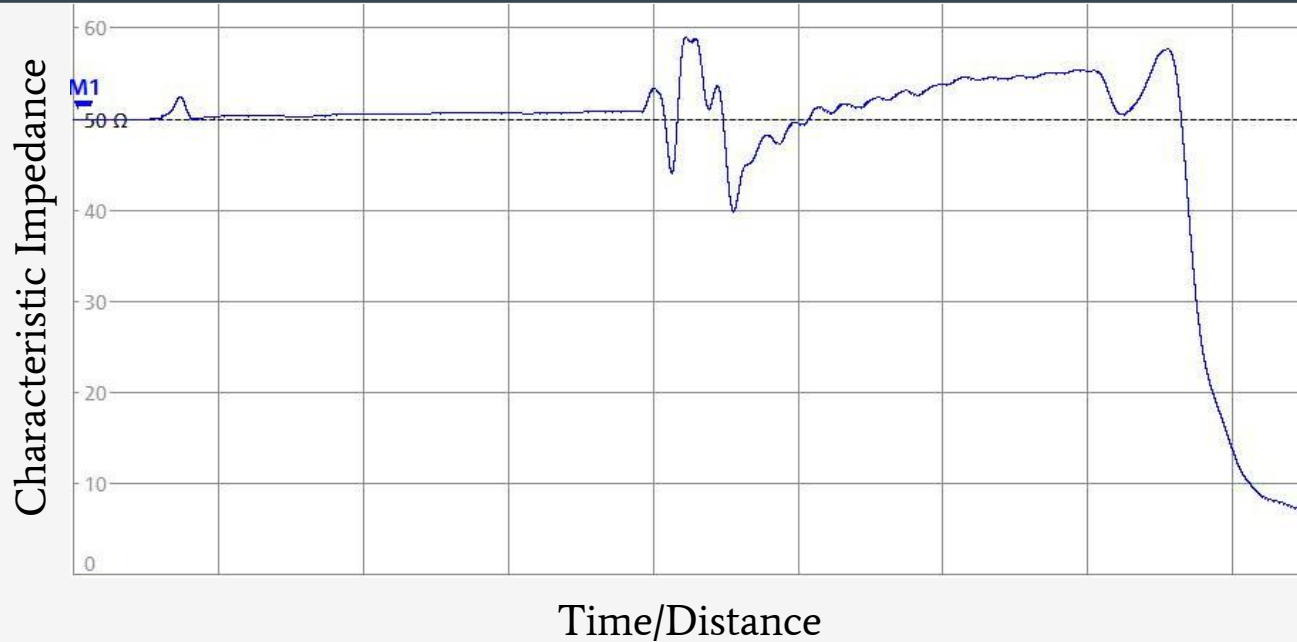
FFT



[Vector Network Analyser]

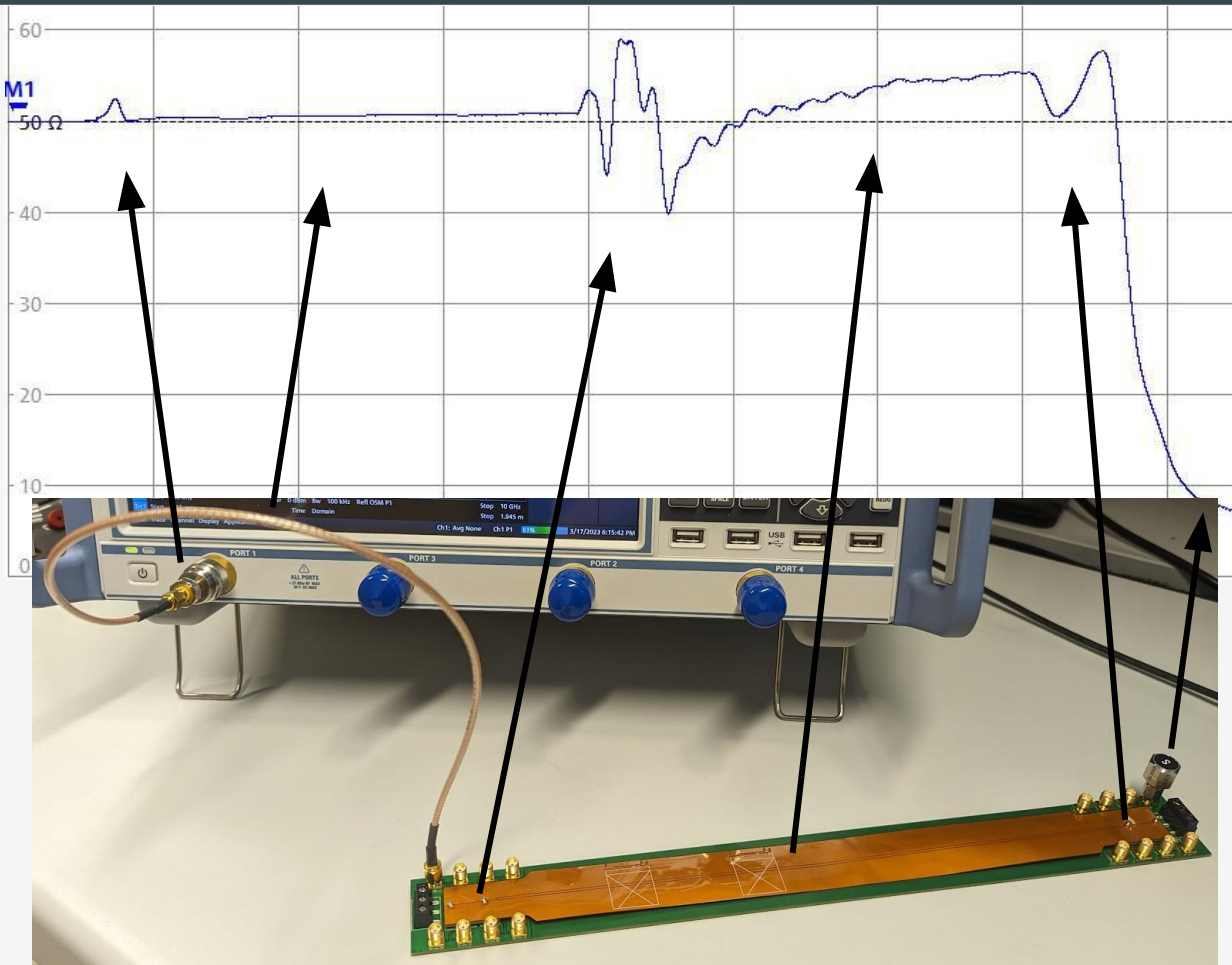


# Time Domain Reflectometry

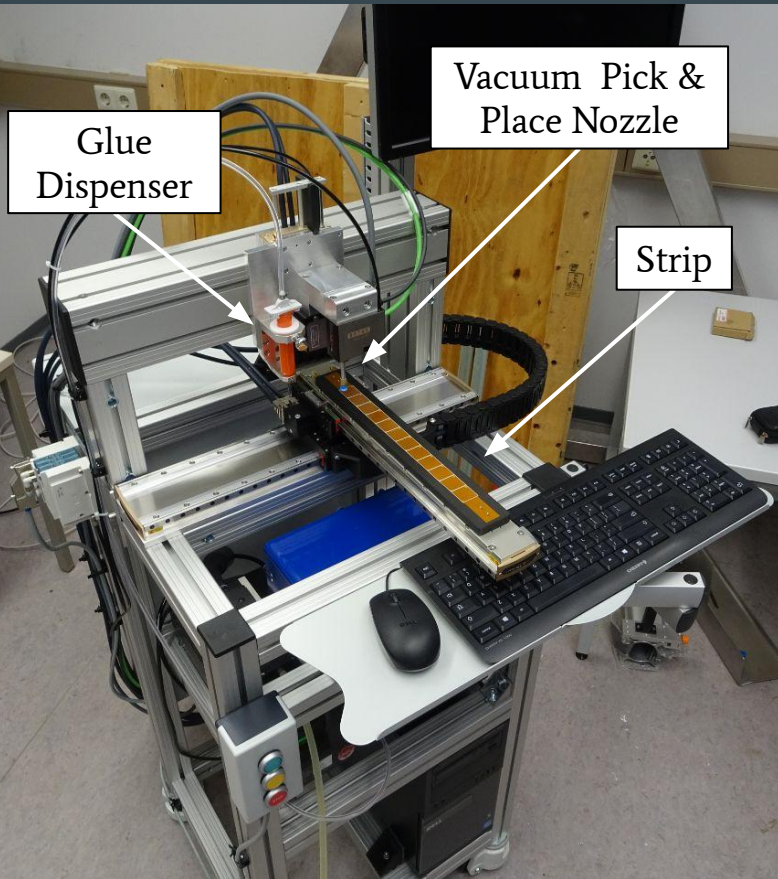


# Time Domain Reflectometry

Characteristic Impedance

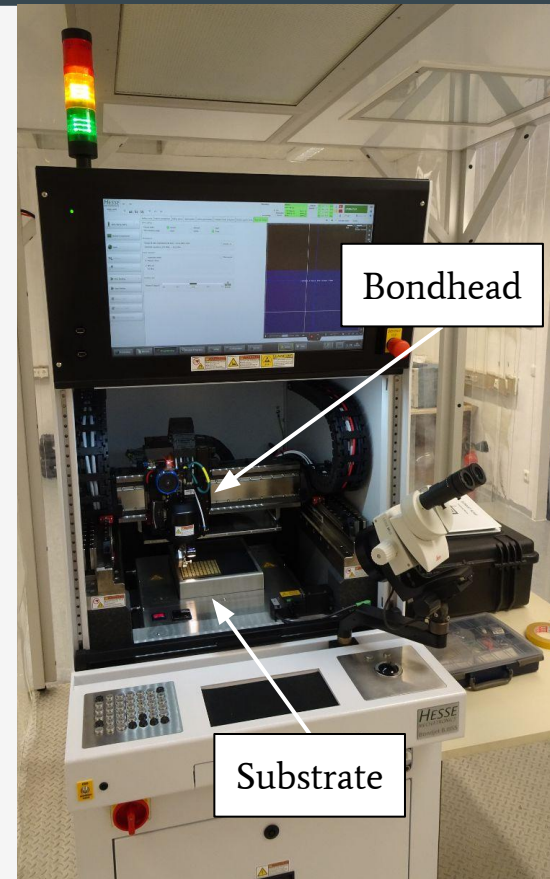
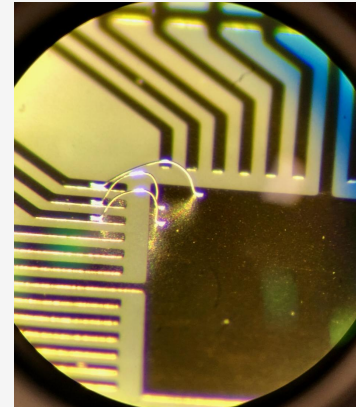


# Mounting of Sensors



Gluebot

- Precise glue dispenser + pick & place machine
- Wire-bonding using aluminium wire
- Production of all 260 strips in Mainz  
→ semi-automated processes



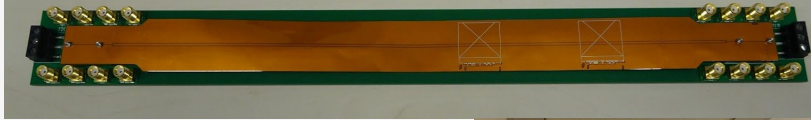
Wire-Bonding Machine

# Outlook



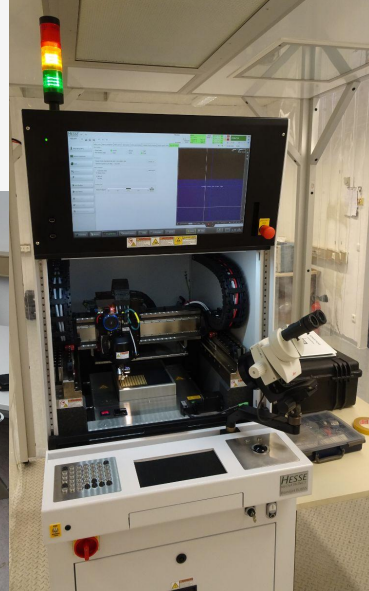
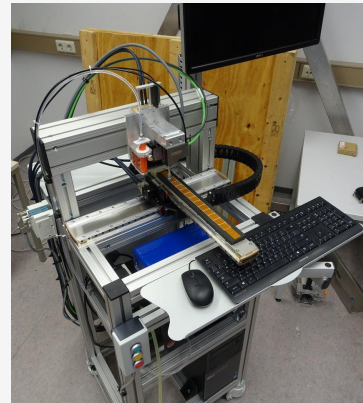
## Soldered Rigid-Flex

- Promising first results
- Electrical Properties with Test Jig (signal integrity @ 1.25 Gbit/s)
- Mechanical Tests (tension, climate chamber)
- Final Routing of Signals (10 differential lines + some single ended lines)



## Gluing & Wire Bonding

- Glue Dispense & Wire Bonding parameters
- Placement Precision of Gluebot
- Semi-automation of processes (pattern recognition etc.)



# Outlook



## Soldered Rigid-Flex

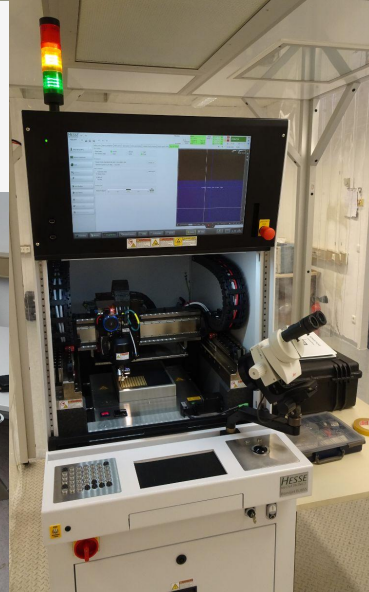
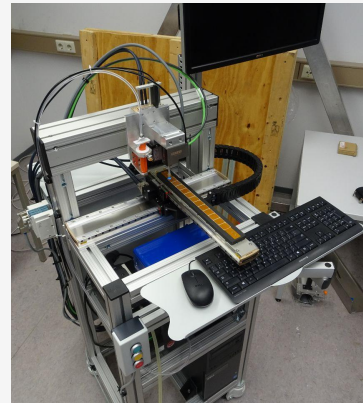
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Thanks for your  
attention!



## Gluing & Wire Bonding

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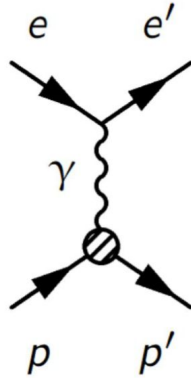
Backup



# P2 - Theory

The weak mixing angle  
(Weinberg-angle):

$$\sin^2 \theta_W = \frac{g'^2}{g^2 + g'^2}$$

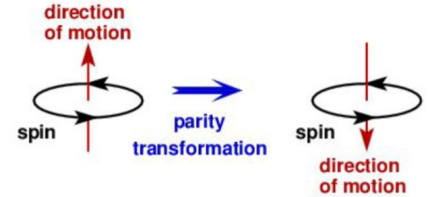


Proton electric charge  
+1



Proton weak charge  
 $1 - 4 \sin^2 \theta_W$

**Violates parity!**



Parity violating asymmetry

momentum transfer

Asymmetry: 
$$A_{PV} = \frac{G_F Q^2}{4\sqrt{2}\pi\alpha} \left( 1 - 4 \sin^2 \theta_W - F(Q^2) \right)$$

proton form factor  
(small @ low  $Q^2$ )

# P2 - Experiment

## Measuring the parity violating asymmetry in e-p-scattering

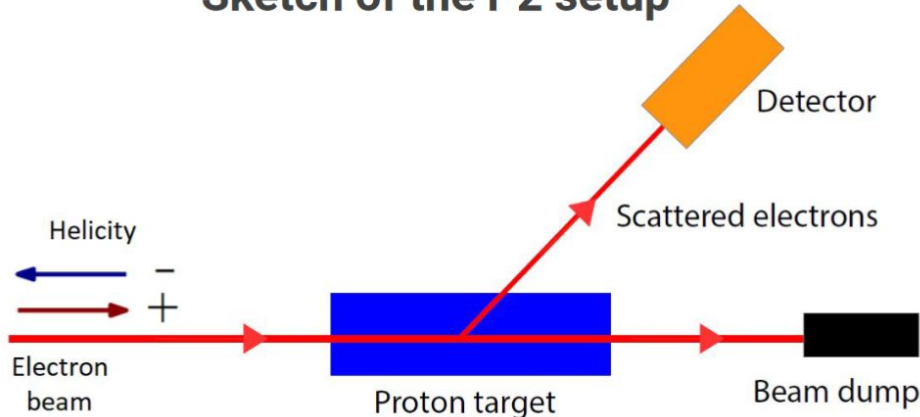
polarization of the beam

$$A_{exp} \equiv \frac{N^+ - N^-}{N^+ + N^-} = P_{beam} \cdot \langle A_{pv} \rangle + A_{app} \sim \underline{30 \text{ ppb}}$$

averaged expected value

apparative asymmetry

### Sketch of the P2 setup



### Beam:

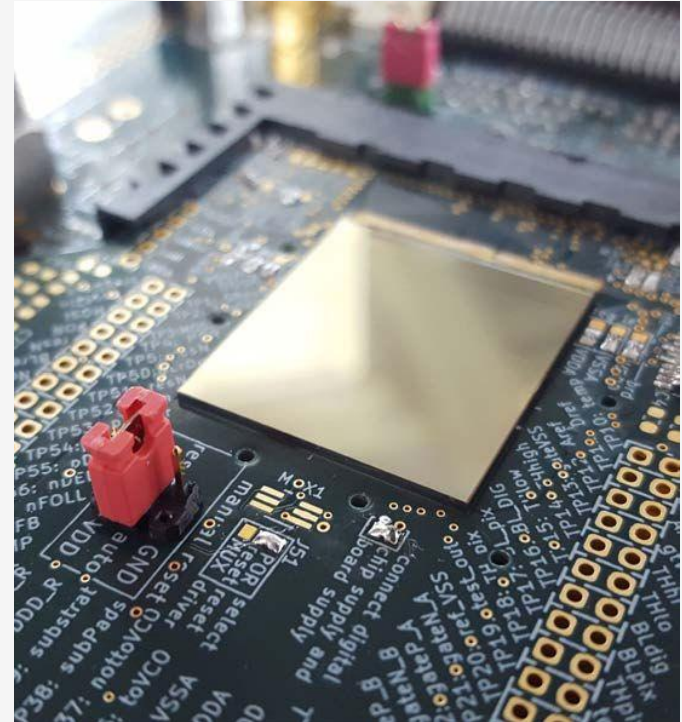
- Highly polarized ( $\geq 85\%$ )
- Current:  $150 \mu\text{A} = 10^{15} \text{ e}^-/\text{s}$
- $L \approx 2.4 \cdot 10^{39} \text{ cm}^{-2}\text{s}^{-1}$
- Energy: 155 MeV
- Flip helicity @ 1 kHz

### Additional requirement:

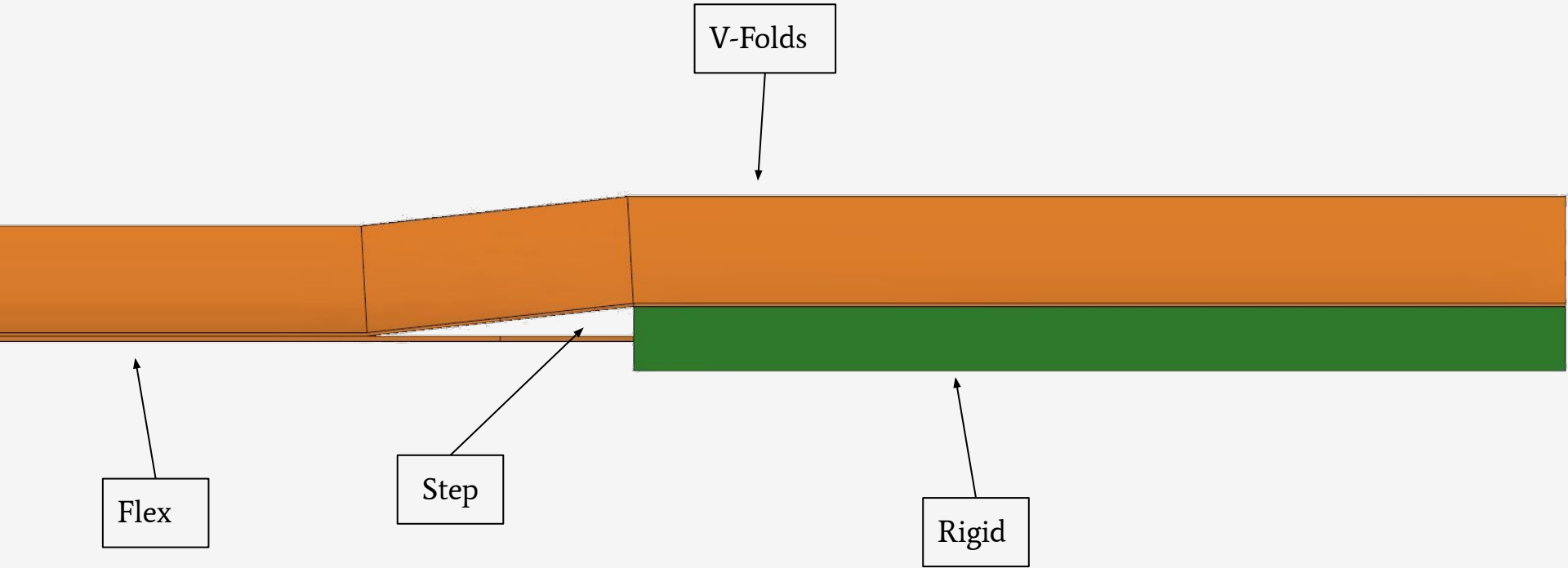
- Beam polarization:  
 $\Delta P_b / P_b \leq 0.5\%$

# MuPix 10

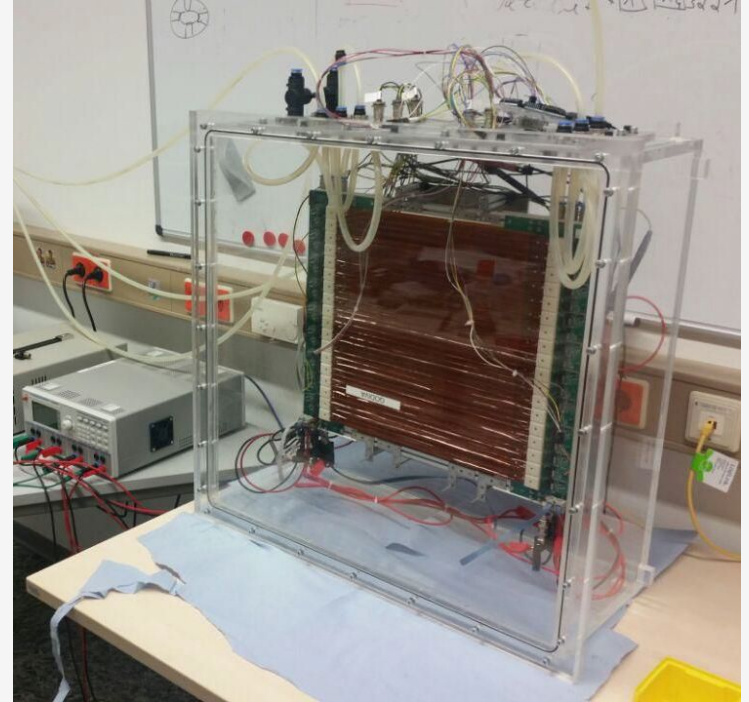
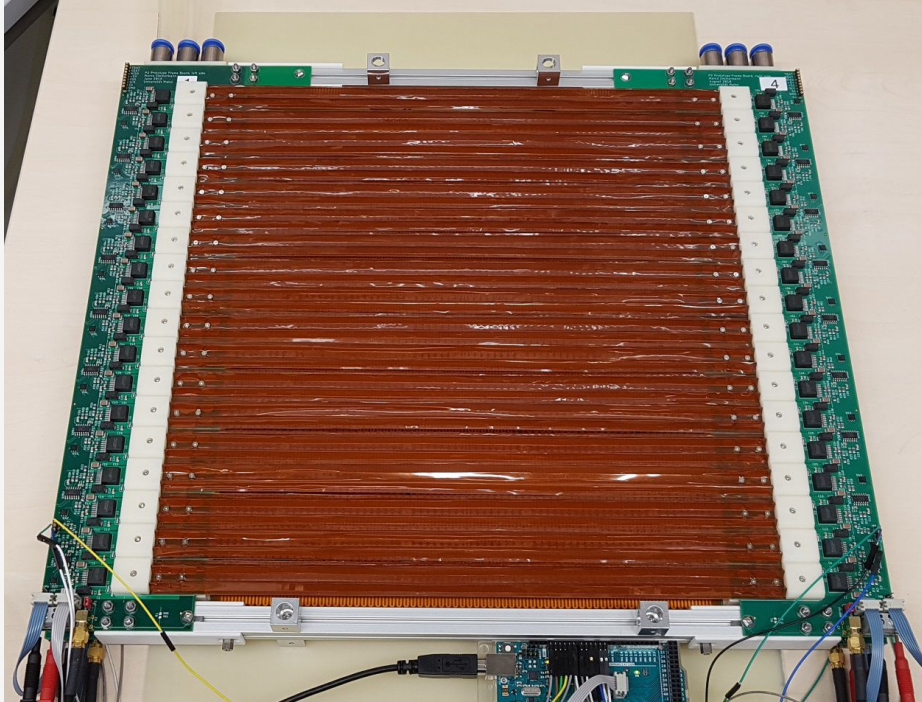
- HV-MAPS - High voltage monolithic active pixel sensors (Ivan Perić)
- Based on 180 nm HV-CMOS process
- Can be thinned down to  $< 50 \mu\text{m}$
- Pixel Matrix  $256 \times 250$
- Pixel Size  $80 \mu\text{m} \times 80 \mu\text{m}$
- Active Area  $20.40 \text{ mm} \times 20 \text{ mm}$
- Efficiency  $> 99\%$
- Noise Rate  $< 2 \text{ Hz / Pixel}$
- Power Consumption  $< 200 \text{ mW / cm}^2$



# Symmetrischer Layerstack & V-Folds



# Thermo Mechanical Prototype



[Marco Zimmermann & Michail Kravchenko]